

**Amendments to the Claims:**

Please delete claims 5, ~~7~~, 12-~~17~~, 19-~~21~~ and ~~23~~ without prejudice to or disclaimer of the subject matter contained therein. Applicant reserves the right to file a divisional application to pursue these claims.

The following listing of claims will replace all prior versions, and listings, of claims in the application:

A 1. (Currently Amended) A method that exposes a second object by transferring a pattern of a first object with an exposure beam, in which ~~and successively exposes a plurality of divided regions having different target exposure levels defined on said second object, are successively exposed by emitting pulses of the exposure beams~~ beam from a pulsed energy source and moving said first object and said second object synchronously in relation to said second object with respect to the exposure beam, the method ~~comprising the steps of:~~

setting a transmittance of a light reducing member disposed in an optical path of the exposure beam based on at least one target exposure level,

wherein the transmittance is determined so as to satisfy a predetermined condition when exposing a divided region having a minimum target exposure level;

~~adjusting an exposure level control parameters~~ a parameter when exposing the divided regions having different target exposure levels ~~according to individual target exposure levels~~ without changing the ~~selected~~ determined transmittance of the light reducing member.

2. (Currently Amended) A method according to claim 1, wherein said ~~exposure level control parameters include~~ parameter includes at least one ~~parameter from a group of parameters that includes~~ of a width of the exposure beam on the second object in the moving direction of the second object, a moving speed of the second object during the synchronous

movement, an oscillation frequency of the exposure beam ~~produced by the pulsed energy~~ source, and an energy of the exposure beam emitted from the pulsed energy source.

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3. (Currently Amended) A method according to claim 1, wherein said transmittance of the light reducing member is determined according to ~~a~~ the minimum target exposure level in the plurality of exposure levels.

4. (Currently Amended) A method according to claim 1, wherein said target exposure levels are ~~assigned to individual regions~~ determined for the plurality of divided regions respectively, according to distances from a center of the second object.

5. (Canceled). ✓

6. (Currently Amended) A method according to claim 51, wherein said target exposure levels for ~~a~~ the plurality of divided regions ~~is~~ are predetermined by ~~exposure testing using an object that is deemed equivalent to the second object~~ performing a test exposure.

7. (Canceled). ✓

8. (Currently Amended) A method according to claim 51, wherein ~~a light reducing member alters transmittance of the exposure beam by switching luminance of the exposure beam on the second object over several stages, and~~

~~—— a common value of transmittance is used for exposing different divided regions~~ the exposure conditions is related to the number of pulses of the exposure beam directed to the second object.

9. (Currently Amended) A method according to claim 81, wherein said ~~transmittance of light reducing member is chosen based on a minimum value of exposure level selected from a plurality of target exposure levels for a plurality of divided regions defined on the second object~~ the second object is a wafer.

10. (Currently Amended) An apparatus that illuminates a first object with an exposure beam and that successively exposes a plurality of divided regions defined on a second object with said exposure beam, comprising:

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an illumination system having a pulsed light source that generates pulses of light to serve as an other exposure beam and a light attenuator disposed in a path of the exposure beam;

a stage system that moves the first object synchronously with the second stage having a first stage and a second stage, the first stage and the second stage being moved synchronously, and the first object disposed on the first stage and the second object disposed on the second stage;

a memory section that stores target exposure levels in a plurality of different levels for the a plurality of divided regions defined on the second object wherein a transmittance of the light attenuator is determined so as to satisfy a predetermined condition when exposing a divided region having a minimum exposure target level;

a control system that changes at least one an exposure parameter when successively exposing the plurality of divided regions defined on the second object according to based on the target exposure levels stored in the memory section without changing the determined transmittance, wherein said one exposure parameter includes oscillation frequency of the pulsed light source, target per pulse energy of each of the pulses emitted from the pulsed light source, and speed of scanning the second object controlled by the stage system stage during the synchronous movement.

11. (Currently Amended) ~~A method~~ An apparatus according to claim 10, wherein said light attenuator has a light reducing member is to be provided between said pulsed light source and said second object to switch said transmittance of the exposure beam in a plurality of stages.

12-17. (Canceled). ✓

18. (Currently Amended) A method of manufacturing a device including the steps of imprinting a process for forming a device pattern on a work-piece using an the exposure method according to claim 1.

19-21. (Canceled). ✓

22. (Currently Amended) A method of manufacturing an electronic device including ~~the steps of imprinting~~ a process for forming a device pattern on a work-piece using ~~an~~ the exposure apparatus according to claim 10.

23. (Canceled). ✓

24. (New) An exposure method in which a plurality of divided regions having different target exposure levels on a second object are successively exposed, the method comprising:

determining a transmittance of a light attenuator disposed in an optical path of an exposure beam so as to satisfy a predetermined condition when exposing a divided region having a minimum target exposure level; and

exposing the plurality of divided regions having different target exposure levels on said second object without changing the transmittance of the light attenuator.

25. (New) A method according to claim 24, the transmittance of the light attenuator is determined so that the number of exposure pulses for the divided region having the minimum target exposure level is equal to or more than the predetermined minimum number of exposure pulses.

26. (New) A method according to claim 25, further comprising:

synchronously moving the first object and the second object to expose each of the plurality of divided regions on the second object; and

changing an exposure parameter includes at least one of a width of the exposure beam on the second object in the moving direction of the second object, a moving speed of the second object during the synchronous movement, an oscillation frequency of the pulsed energy source, and an energy of the exposure beam emitted from the pulsed energy source, during the exposure for the plurality of divided regions having different target exposure levels on said second object.

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27. (New) A method according to claim 26, wherein said exposure levels are determined for the plurality of divided regions respectively, in accordance with distances from a center of the second object.

28. (New) A method according to claim 26, wherein the second object is a wafer.

29. (New) A device manufacturing method including a process for forming a device pattern on the wafer using the exposure method of claim 24.

30. (New) An exposure apparatus in which a plurality of divided regions having different target exposure levels on a wafer are successively exposed, the apparatus comprising:

means for determining a transmittance of a light attenuator disposed in an optical path of an exposure beam so as to satisfy a predetermined condition when exposing a divided region having a minimum target exposure level; and

means for exposing the plurality of divided regions having different target exposure levels on the wafer without changing the transmittance of the light attenuator.

31. (New) A device manufacturing method including a process for forming a device pattern on the wafer using the exposure apparatus of claim 30.